



Material Content Data Sheet



Sales Product Name		SPD50P03L G		Issued		1. August 2018		
MA#		MA001626260						
Package		PG-TO252-5-13		Weight*		429.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.993	0.70	0.70	6970	6970
leadframe	inorganic material	phosphorus	7723-14-0	0.088	0.02		205	
	non noble metal	iron	7439-89-6	0.293	0.07		682	
	non noble metal	copper	7440-50-8	292.340	68.09	68.18	680831	681718
	non noble metal	aluminium	7429-90-5	2.020	0.47	0.47	4705	4705
wire	inorganic material	antimonytrioxide	1309-64-4	1.730	0.40		4028	
encapsulation	plastics	brominated resin	-	1.853	0.43		4316	
	organic material	carbon black	1333-86-4	1.977	0.46		4604	
	plastics	epoxy resin	-	16.678	3.88		38842	
	inorganic material	silicondioxide	60676-86-0	101.305	23.59	28.76	235930	287720
leadfinish	non noble metal	tin	7440-31-5	5.440	1.27	1.27	12670	12670
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.089	0.02	0.02	206	207
solder	non noble metal	tin	7440-31-5	0.052	0.01		120	
	noble metal	silver	7440-22-4	0.065	0.02		150	
	non noble metal	lead	7439-92-1	2.465	0.57	0.60	5740	6010
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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